

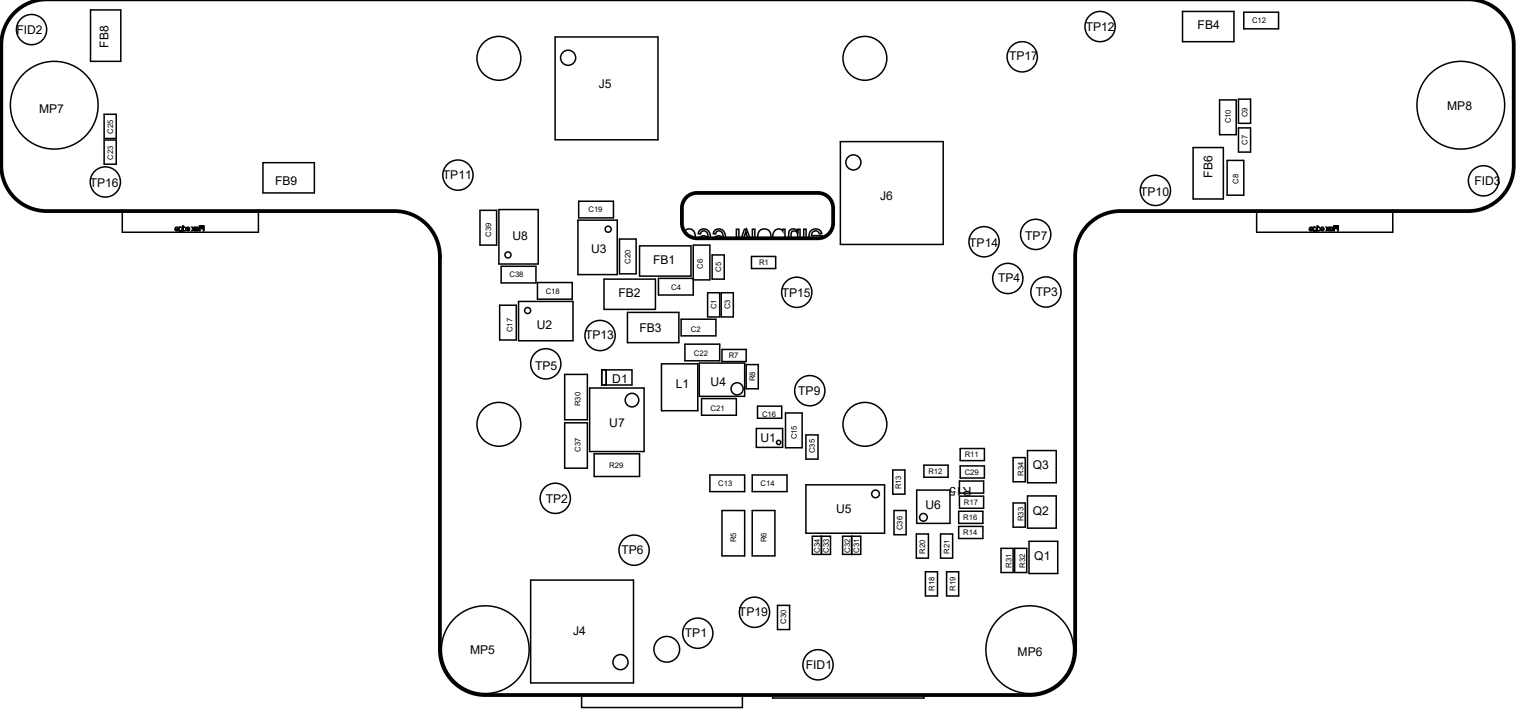
ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.
Assembly shall conform with RoHS Directive 2011/65/EU.
Components shall be placed according to the associated CPL and BOM documents.
Lead-free SAC305 solder shall be used.
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
BGA components shall be 100% checked with x-ray for solder bridges after reflow.
Finished assemblies shall be removed from panel prior to delivery.

Notes:

- 1
- Note 1
- 2
- Note 2
- 3
- Note 3

View from Top side (Scale 2)



Title: BW1098OBC	
Number: DXXXX	Revision: R1M0 E1
Date: 4/21/2020	Sheet: 1 of 2
Drawn by: Brian Weinstein	



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A

B

C

D

E

1

1

2

2

3

3

4

4

[Variant: [All Variants]]: View from Bottom side (Scale 2)

